

# Contract Services

At Compex, we are glad to assist in your application any way we can. All of our processing capabilities are available to meet our customers' requirements, from providing bare substrates and custom plating, to high-speed packaging. Our more common services include the following:

- **Substrates**

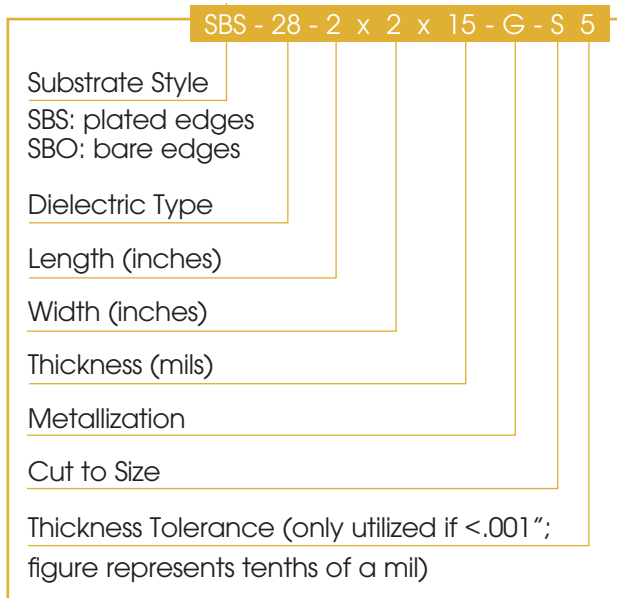
Compex stocks a full line of Alumina, AlN, Quartz, and custom ceramic wafers which can be supplied bare or plated.

- **Plating**

Compex offers various Thin Film Deposition options. Plating runs as small as one wafer depending on metallization.

## Substrates Part Number Assembly

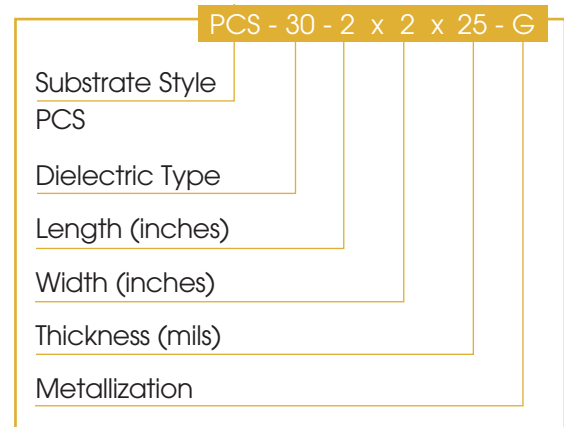
Example: Compex Series SBS, dielectric type C-28, 2" x 2" x .015", gold with plated edges, thickness tolerance  $\pm .0005$



See Class I and Class II tables (page 4)

## Plating Part Number Assembly

Example: Compex Series PCS, dielectric type C-30, 2" x 2" x .025", gold with plated edges



- **Component Processing**

We provide high-speed testing, automated inspection/packaging, and re-packaging services for a variety of components as small as .007" square. Let our state-of-the-art equipment and 35+ years experience work for you.

*Please contact us for all of your processing needs.*